Status

Multilayer Ceramic Chip Capacitors

Production







1 of 3 Creation Date : April 24, 2017 (GMT)



C1608JB1E225K080AB

TDK item description C1608JB1E225KT****		
Applications	Commercial Grade	
Feature	General General (Up to 50V)	
Series	C1608 [EIA 0603]	



Size		
Length(L)	1.60mm ±0.10mm	
Width(W)	0.80mm ±0.10mm	
Thickness(T)	0.80mm ±0.10mm	
Terminal Width(B)	0.20mm Min.	
Terminal Spacing(G)	0.30mm Min.	
Recommended Land Pattern (PA)	0.70mm to 1.00mm(Flow Soldering)	
Recommended Land Fattern (FA)	0.60mm to 0.80mm(Reflow Soldering)	
Recommended Land Pattern (PB)	0.80mm to 1.00mm(Flow Soldering)	
Recommended Land Fattern (FB)	0.60mm to 0.80mm(Reflow Soldering)	
Recommended Land Pattern (PC)	0.60mm to 0.80mm(Flow Soldering)	
neconiniente a Land Fattern (FC)	0.60mm to 0.80mm(Reflow Soldering)	

Electrical Characteristics		
Capacitance	2.2μF ±10%	
Rated Voltage	25VDC	
Temperature Characteristic	JB(±10%)	
Dissipation Factor (Max.)	10%	
Insulation Resistance (Min.)	227ΜΩ	

Other		
Soldering Method	Wave (Flow)	
	Reflow	
AEC-Q200	No	
Packing	Punched (Paper)Taping [180mm Reel]	
Package Quantity	4000pcs	

[!] Images are for reference only and show exemplary products.

[!] This PDF document was created based on the data listed on the TDK Corporation website.

[!] All specifications are subject to change without notice.

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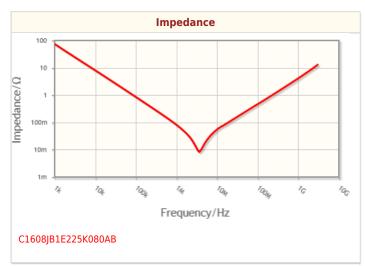




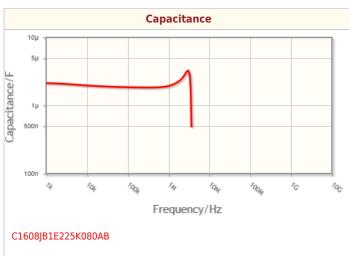


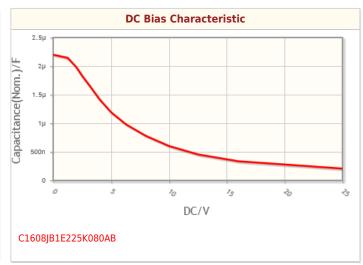


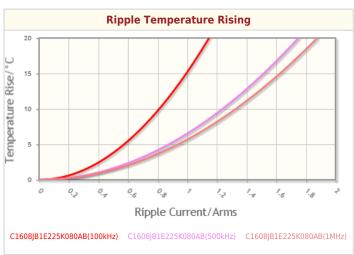
Characteristic Graphs(This is reference data, and does not guarantee the products characteristics.)











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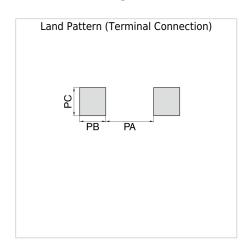








Associated Images



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